Materials Declaration

Package	SSOP
Body Size	5.3 mm
LeadCount	28
Option	Pb Free

Molding Compound

Item	% of Compound	Weight (g)	PPM
Epoxy resin	10	1.35 E-02	61959
SiO2 Filler	85	1.15 E-01	526656
Phenol Resin	3	4.06 E-03	18588
Antimony_Sb2O3	1.5	2.03 E-03	9294
Brominated Resin	0.5	6.77 E-04	3098

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	97.5	6.50 E-02	297407
Fe	2.35	1.57 E-03	7168
P	0.03	2.00 E-05	92
Zn	0.12	8.00 E-05	366

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	9.82 E-04	4497

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100	3.58 E-03	16387

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	8.18 E-04	3743

Chip

	% of Chip	Weight (g)	PPM
Si	**100**	9.99 E-03	45729

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	25	2.74 E-04	1254
Ag Filler	75	8.22 E-04	3763

Package Totals

Weight (g)	PPM
2.18 E-01	1000000

Molding Compound

Item	PPM	Method
Pb	<2	US EPA method #3052 & 6010B
Cd	Not Detected	BS EN 1122:2001 ICP AES
Hg	<2	US EPA method #3052 & 7471A
Cr+6	<2	US EPA method #3060A & 6010B

Die Attach Paste

Item	PPM	Method
Pb	<5	ICP AES
Cd	<5	ICP AES
Hg	<5	ICP AES
Cr+6	<5	ICP AES
PBB	Not Detected	
PBDE	Not Detected	

Note: The information provided in this declaration are true to the best of ADI's knowledge
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability tc
any inaccuracy of such information.

Materials Declaration

Package	SSOP
Body Size	5.3 mm
LeadCount	28
Option	Sn/Pb

Molding Compound

Item	% of Compound	Weight (g)	PPM
Epoxy resin	10	1.35 E-02	61959
SiO2 Filler	85	1.15 E-01	526656
Phenol Resin	3	4.06 E-03	18588
Antimony_Sb2O3	1.5	2.03 E-03	9294
Brominated Resin	0.5	6.77 E-04	3098

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	97.5	6.50 E-02	297407
Fe	2.35	1.57 E-03	7168
P	0.03	2.00 E-05	92
Zn	0.12	8.00 E-05	366

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	9.82 E-04	4497

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85	3.04 E-03	13929
Pb	15	5.37 E-04	2458

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	8.18 E-04	3743

Chip

	% of Chip	Weight (g)	PPM
Si	**100**	9.99 E-03	45729

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	25	2.74 E-04	1254
Ag Filler	75	8.22 E-04	3763

Package Totals

Weight (g)	PPM
2.18 E-01	1000000

Molding Compound

Item	PPM	Method
Pb	<2	US EPA method #3052 & 6010B
Cd	Not Detected	BS EN 1122:2001 ICP AES
Hg	<2	US EPA method #3052 & 7471A
Cr+6	<2	US EPA method #3060A & 6010B

Die Attach Paste

Item	PPM	Method
Pb	<5	ICP AES
Cd	<5	ICP AES
Hg	<5	ICP AES
Cr+6	<5	ICP AES
PBB	Not Detected	
PBDE	Not Detected	

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